





#### NPN SURFACE MOUNT TRANSIS

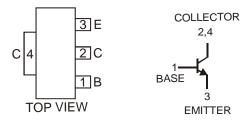
#### **Features**

- **Epitaxial Planar Die Construction**
- Complementary PNP Type Available (DXT3906)
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- Lead Free By Design/RoHS Compliant (Note 1)
- "Green" Device (Note 2)

## **Mechanical Data**

- Case: SOT89-3L
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish Matte Tin annealed over Copper leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking & Type Code Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.072 grams (approximate)





Schematic and Pin Configuration

# **Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	60	V
Collector-Emitter Voltage	V <sub>CEO</sub>	40	V
Emitter-Base Voltage	V <sub>EBO</sub>	6.0	V
Collector Current – Continuous	Ic	200	mA

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3) @ T <sub>A</sub> = 25°C	P <sub>D</sub>	1	W
Thermal Resistance, Junction to Ambient Air (Note 3) @ T <sub>A</sub> = 25°C	$R_{ heta JA}$	125	°C/W
Operating and Storage Temperature Range	T <sub>i</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes:

- No purposefully added lead.
- Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.

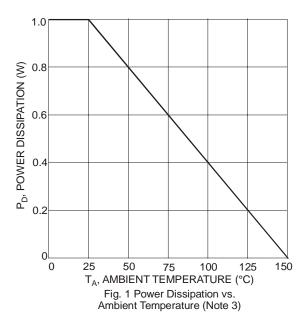
  Device mounted on FR-4 PCB; pad layout as shown on page 4 or in Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

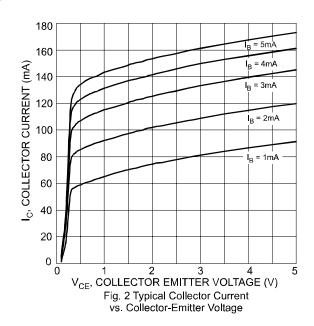


# **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

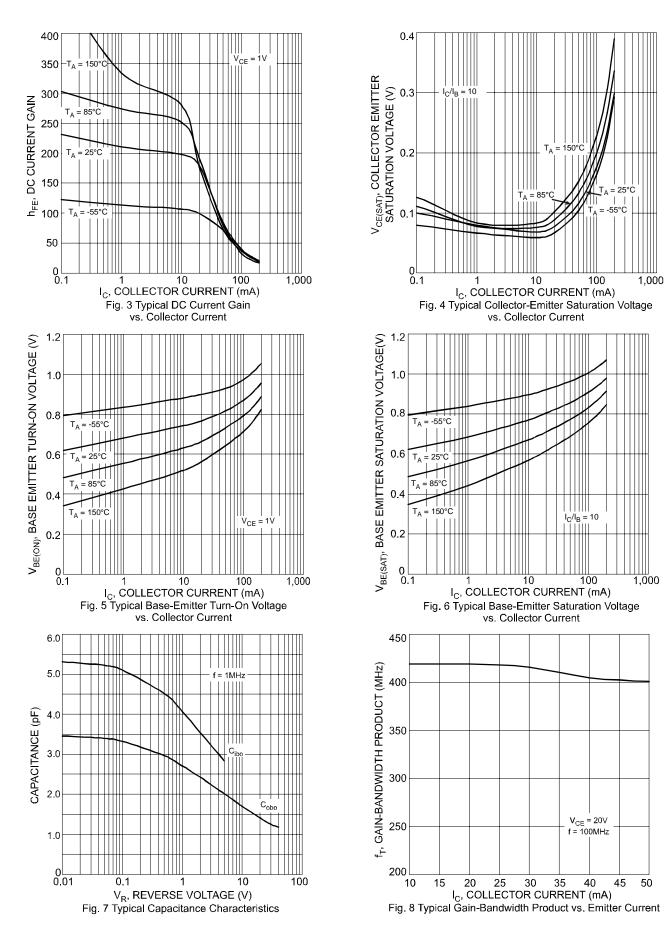
Characteristic	Symbol	Min	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 4)						
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	60		V	$I_C = 10\mu A, I_E = 0$	
Collector-Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	40		V	$I_C = 1.0 \text{mA}, I_B = 0$	
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	6.0		V	$I_E = 10\mu A, I_C = 0$	
Collector Cutoff Current	I <sub>CEX</sub>		50	nA	$V_{CE} = 30V, V_{EB(OFF)} = 3.0V$	
Base Cutoff Current	I <sub>BL</sub>		50	nA	$V_{CE} = 30V, V_{EB(OFF)} = 3.0V$	
ON CHARACTERISTICS (Note 4)					_	
DC Current Gain	h <sub>FE</sub>	40 70 100 60 30	 300  	_	$\begin{split} I_C &= 100 \mu A, \ V_{CE} = 1.0 V \\ I_C &= 1.0 m A, \ V_{CE} = 1.0 V \\ I_C &= 10 m A, \ V_{CE} = 1.0 V \\ I_C &= 50 m A, \ V_{CE} = 1.0 V \\ I_C &= 100 m A, \ V_{CE} = 1.0 V \end{split}$	
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	_	0.20 0.30	V	$I_C = 10\text{mA}, I_B = 1.0\text{mA}$ $I_C = 50\text{mA}, I_B = 5.0\text{mA}$	
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	0.65	0.85 0.95	V	$I_C = 10 \text{mA}, I_B = 1.0 \text{mA}$ $I_C = 50 \text{mA}, I_B = 5.0 \text{mA}$	
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C <sub>obo</sub>		4.0	pF	$V_{CB} = 5.0V$ , $f = 1.0MHz$ , $I_E = 0$	
Input Capacitance	Cibo	_	8.0	pF	$V_{EB} = 0.5V$ , $f = 1.0MHz$ , $I_C = 0$	
Input Impedance	h <sub>ie</sub>	1.0	10	kΩ	V <sub>CE</sub> = 10V, I <sub>C</sub> = 1.0mA, f = 1.0kHz	
Voltage Feedback Ratio	h <sub>re</sub>	0.5	8.0	x 10 <sup>-4</sup>		
Small Signal Current Gain	h <sub>fe</sub>	100	400	_		
Output Admittance	h <sub>oe</sub>	1.0	40	μS		
Current Gain-Bandwidth Product	f⊤	300		MHz	V <sub>CE</sub> = 20V, I <sub>C</sub> = 10mA, f = 100MHz	
Noise Figure	NF	_	5.0	dB	$V_{CE} = 5.0V, I_C = 100\mu A,$ $R_S = 1.0k\Omega, f = 1.0kHz$	
SWITCHING CHARACTERISTICS						
Delay Time	t <sub>d</sub>	_	35	ns	$V_{CC} = 3.0V, I_{C} = 10mA,$	
Rise Time	t <sub>r</sub>	_	35	ns	$V_{BE(off)} = -0.5V, I_{B1} = 1.0mA$	
Storage Time	ts	_	200	ns	$V_{CC} = 3.0V, I_{C} = 10mA,$	
Fall Time	t <sub>f</sub>		50	ns	$I_{B1} = I_{B2} = 1.0 \text{mA}$	

Notes: 4. Measured under pulsed condition. Pulse width =  $300\mu s$ . Duty cycle  $\leq 2\%$ .









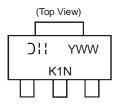


## **Ordering Information (Note 5)**

Device	Packaging	Shipping
DXT3904-13	SOT89-3L	2500/Tape & Reel

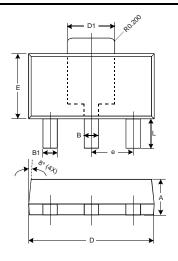
For packaging details, go to our website at http://www.diodes.com/ap02007.pdf.

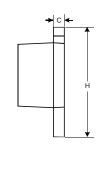
# **Marking Information**



K1N = Product Type Marking Code YWW = Date Code Marking Y = Last digit of year ex: 7 = 2007 WW = Week code 01 - 52

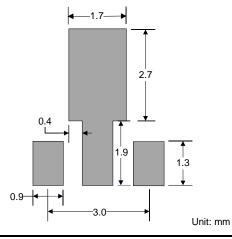
# **Package Outline Dimensions**





SOT89-3L				
Dim	Min	Max	Тур	
Α	1.40	1.60	1.50	
В	0.45	0.55	0.50	
B1	0.37	0.47	0.42	
C	0.35	0.43	0.38	
D	4.40	4.60	4.50	
D1	1.50	1.70	1.60	
Е	2.40	2.60	2.50	
е	_	_	1.50	
Н	3.95	4.25	4.10	
L	0.90	1.20	1.05	
All Dimensions in mm				

# **Suggested Pad Layout**



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